# IR2112(-1-2)(S)PbF

#### HIGH AND LOW SIDE DRIVER

#### **Features**

- · Floating channel designed for bootstrap operation
- Fully operational to +600V
- Tolerant to negative transient voltage dV/dt immune
- Gate drive supply range from 10 to 20V
- · Undervoltage lockout for both channels
- 3.3V logic compatible
   Separate logic supply range from 3.3V to 20V
   Logic and power ground ±5V offset
- CMOS Schmitt-triggered inputs with pull-down
- Cycle by cycle edge-triggered shutdown logic
- Matched propagation delay for both channels
- · Outputs in phase with inputs

## Description

The IR2112(S) is a high voltage, high speed power MOSFET and IGBT driver with independent high and low side referenced output channels. Proprietary HVIC and latch immune CMOS technologies enable ruggedized monolithic construction. Logic inputs are com-

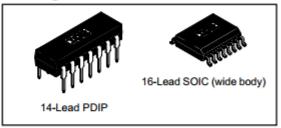
patible with standard CMOS or LSTTL outputs, down to 3.3V logic.

The output drivers feature a high pulse current buffer stage designed for minimum driver cross-conduction.

### **Product Summary**

Voffset	600V max.
I <sub>O</sub> +/-	200 mA / 420 mA
Vout	10 - 20V
t <sub>on/off</sub> (typ.)	125 & 105 ns
Delay Matching	30 ns

#### Packages 4 8 1



LOAD

Propagation delays are matched to simplify use in high frequency applications. The floating channel can be used to drive an N-channel power MOSFET or IGBT in the high side configuration which operates up to 600 volts.

Typical Connection

Up to 600V

(Refer to Lead Assignments for correct pin configuration). This/These diagram(s) show electrical connections only. Please refer to our Application Notes and DesignTips for proper circuit board layout.

#### Absolute Maximum Ratings

Absolute Maximum Ratings indicate sustained limits beyond which damage to the device may occur. All voltage parameters are absolute voltages referenced to COM. The Thermal Resistance and Power Dissipation ratings are measured under board mounted and still air conditions. Additional information is shown in Figures 28 through 35.

Symbol	Definition	Min.	Max.	Units	
V <sub>B</sub>	High Side Floating Supply Voltage	-0.3	625		
Vs	High Side Floating Supply Offset Voltage	V <sub>B</sub> - 25	V <sub>B</sub> + 0.3		
V <sub>HO</sub>	High Side Floating Output Voltage	V <sub>S</sub> - 0.3	V <sub>B</sub> + 0.3		
Vcc	Low Side Fixed Supply Voltage	-0.3	25	v	
V <sub>LO</sub>	Low Side Output Voltage		-0.3	V <sub>CC</sub> + 0.3	
V <sub>DD</sub>	Logic Supply Voltage		-0.3	V <sub>SS</sub> + 25	
V <sub>SS</sub>	Logic Supply Offset Voltage	V <sub>CC</sub> - 25	V <sub>CC</sub> + 0.3		
V <sub>IN</sub>	Logic Input Voltage (HIN, LIN & SD)	V <sub>SS</sub> - 0.3	V <sub>DD</sub> + 0.3		
dV₅/dt	Allowable Offset Supply Voltage Transient (Figure 2)		_	50	V/ns
PD	Package Power Dissipation @ T <sub>A</sub> ≤ +25°C (14 Lead DIP)		_	1.6	w
		(16 Lead SOIC)		1.25	l w
R <sub>THJA</sub>	Thermal Resistance, Junction to Ambient (14 Lead DIP)		_	75	°C/W
		(16 Lead SOIC)	_	100	C/W
TJ	Junction Temperature	_	150		
TS	Storage Temperature	-55	150	°C	
TL	Lead Temperature (Soldering, 10 seconds)	_	300		

#### Recommended Operating Conditions

The Input/Output logic timing diagram is shown in Figure 1. For proper operation the device should be used within the recommended conditions. The VS and VSS offset ratings are tested with all supplies biased at 15V differential. Typical ratings at other bias conditions are shown in Figures 36 and 37.

Symbol	Definition	Min.	Max.	Units
V <sub>B</sub>	High Side Floating Supply Absolute Voltage	V <sub>S</sub> + 10	V <sub>S</sub> + 20	
Vs	High Side Floating Supply Offset Voltage	Note 1	600	
V <sub>HO</sub>	High Side Floating Output Voltage	Vs	VB	
V <sub>CC</sub>	Low Side Fixed Supply Voltage	10	20	
V <sub>LO</sub>	Low Side Output Voltage	0	Vcc	V
V <sub>DD</sub>	Logic Supply Voltage	V <sub>SS</sub> + 3	V <sub>SS</sub> + 20	
V <sub>SS</sub>	Logic Supply Offset Voltage	-5 (Note 2)	5	
V <sub>IN</sub>	Logic Input Voltage (HIN, LIN & SD)	V <sub>SS</sub>	V <sub>DD</sub>	
TA	Ambient Temperature	-40	125	°C

Note 1: Logic operational for V<sub>S</sub> of -5 to +600V. Logic state held for V<sub>S</sub> of -5V to -V<sub>BS</sub>. (Please refer to the Design Tip DT97-3 for more details).

Note 2: When VDD < 5V, the minimum Vss offset is limited to -VDD.

## **Dynamic Electrical Characteristics**

V<sub>BIAS</sub> (V<sub>CC</sub>, V<sub>BS</sub>, V<sub>DD</sub>) = 15V, C<sub>L</sub> = 1000 pF, T<sub>A</sub> = 25°C and V<sub>SS</sub> = COM unless otherwise specified. The dynamic electrical characteristics are measured using the test circuit shown in Figure 3.

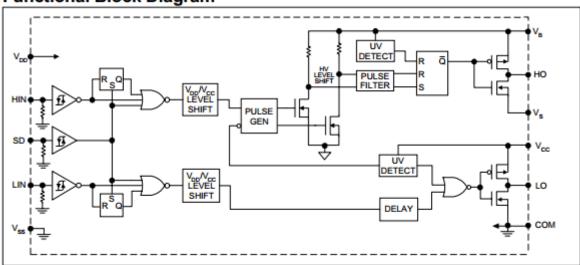
Symbol	Definition	Figure	Min.	Тур.	Max.	Units	Test Conditions
ton	Turn-On Propagation Delay	7	_	125	180		V <sub>S</sub> = 0V
t <sub>off</sub>	Turn-Off Propagation Delay	8	_	105	160	ns	V <sub>S</sub> = 600V
t <sub>sd</sub>	Shutdown Propagation Delay	9	_	105	160		V <sub>S</sub> = 600V
t <sub>r</sub>	Turn-On Rise Time	10	_	80	130		
tf	Turn-Off Fall Time	11	_	40	65		
MT	Delay Matching, HS & LS Turn-On/Off	_	_	_	30		

#### **Static Electrical Characteristics**

 $V_{BIAS}$  ( $V_{CC}$ ,  $V_{BS}$ ,  $V_{DD}$ ) = 15V,  $T_A$  = 25°C and  $V_{SS}$  = COM unless otherwise specified. The  $V_{IN}$ ,  $V_{TH}$  and  $I_{IN}$  parameters are referenced to  $V_{SS}$  and are applicable to all three logic input leads: HIN, LIN and SD. The  $V_O$  and  $I_O$  parameters are referenced to COM and are applicable to the respective output leads: HO or LO.

Symbol	Definition	Figure	Min.	Тур.	Max.	Units	Test Conditions
V <sub>IH</sub>	Logic "1" Input Voltage	12	9.5	_	_	v	
V <sub>IL</sub>	Logic "0" Input Voltage	13	_	_	6.0	ľ	
VoH	High Level Output Voltage, VBIAS - VO	14	_	_	100	mV	I <sub>O</sub> = 0A
V <sub>OL</sub>	Low Level Output Voltage, VO	15	_	_	100	] ""	I <sub>O</sub> = 0A
ILK	Offset Supply Leakage Current	16	_	_	50		V <sub>B</sub> = V <sub>S</sub> = 600V
IQBS	Quiescent V <sub>BS</sub> Supply Current	17	_	25	60		V <sub>IN</sub> = 0V or V <sub>DD</sub>
lacc	Quiescent V <sub>CC</sub> Supply Current	18	_	80	180		V <sub>IN</sub> = 0V or V <sub>DD</sub>
IQDD	Quiescent V <sub>DD</sub> Supply Current	19	_	2.0	5.0	μA	V <sub>IN</sub> = 0V or V <sub>DD</sub>
I <sub>IN+</sub>	Logic "1" Input Bias Current	20	_	20	40		V <sub>IN</sub> = V <sub>DD</sub>
I <sub>IN-</sub>	Logic "0" Input Bias Current	21	_	_	1.0		V <sub>IN</sub> = 0V
VBSUV+	V <sub>BS</sub> Supply Undervoltage Positive Going Threshold	22	7.4	8.5	9.6		
V <sub>BSUV</sub> -	V <sub>BS</sub> Supply Undervoltage Negative Going Threshold	23	7.0	8.1	9.2	v	
V <sub>CCUV+</sub>	V <sub>CC</sub> Supply Undervoltage Positive Going Threshold	24	7.6	8.6	9.6		
Vccuv-	VCC Supply Undervoltage Negative Going Threshold	25	7.2	8.2	9.2		
l <sub>O+</sub>	Output High Short Circuit Pulsed Current	26	200	250	_	mA	V <sub>O</sub> = 0V, V <sub>IN</sub> = V <sub>DD</sub> PW ≤ 10 μs
I <sub>O-</sub>	Output Low Short Circuit Pulsed Current	27	420	500	_	l IIIA	V <sub>O</sub> = 15V, V <sub>IN</sub> = 0V PW ≤ 10 μs

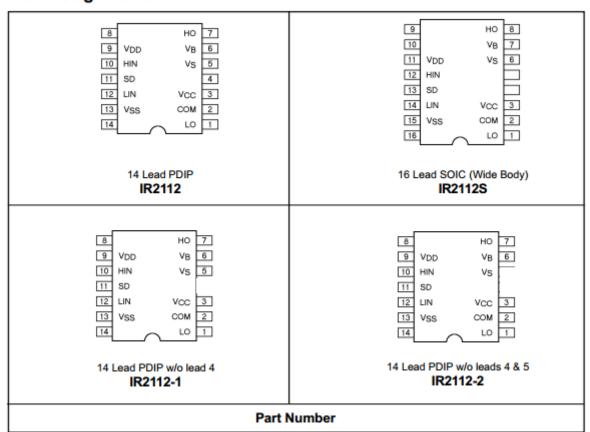
## **Functional Block Diagram**



#### **Lead Definitions**

Symbol	Description			
V <sub>DD</sub>	Logic supply			
HIN	Logic input for high side gate driver output (HO), in phase			
SD	Logic input for shutdown			
LIN	Logic input for low side gate driver output (LO), in phase			
VSS	Logic ground			
VB	High side floating supply			
НО	High side gate drive output			
Vs	High side floating supply return			
Vcc	Low side supply			
LO	Low side gate drive output			
COM	Low side return			

## **Lead Assignments**



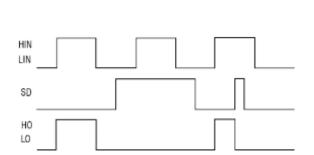


Figure 1. Input/Output Timing Diagram

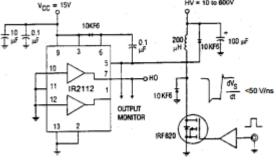


Figure 2. Floating Supply Voltage Transient Test Circuit

